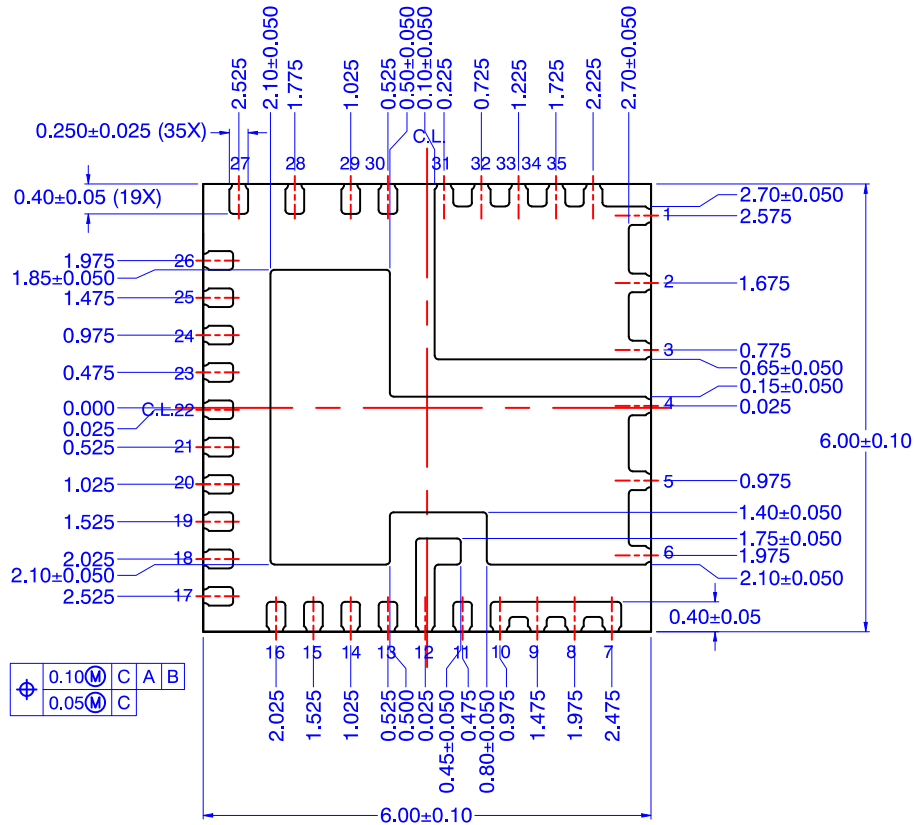
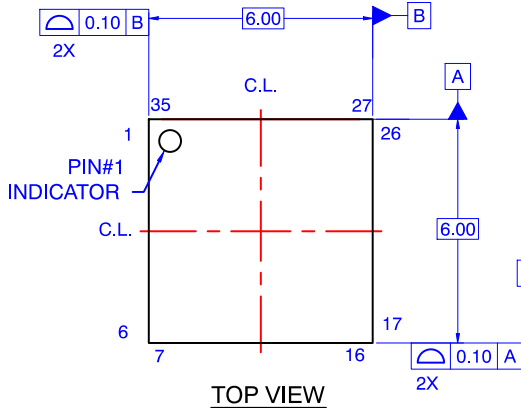


**PQFN35 6X6, 0.5P**  
**CASE 483BE**  
**ISSUE O**

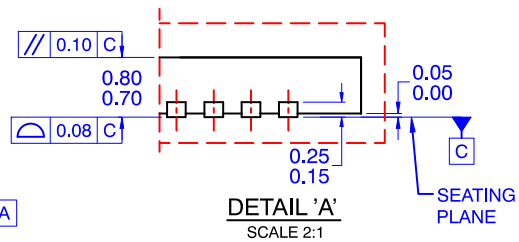
DATE 30 SEP 2016



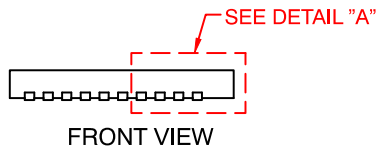
**BOTTOM VIEW**  
 SCALE 2:1



**TOP VIEW**



**DETAIL 'A'**  
 SCALE 2:1

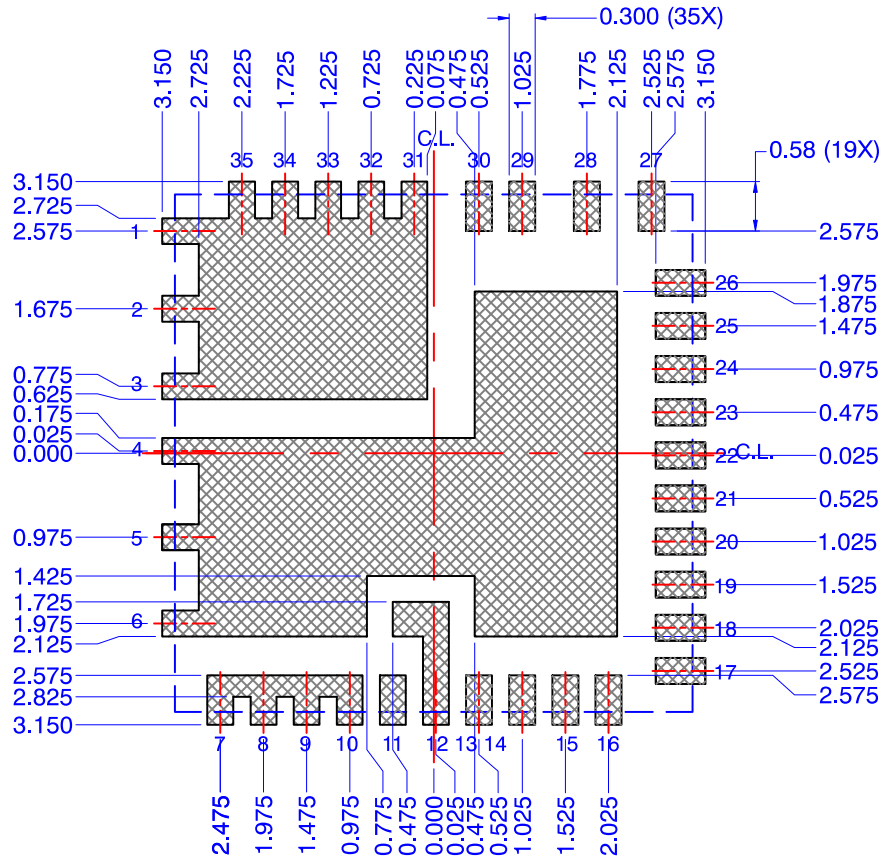


**FRONT VIEW**

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ISSUE O

DATE 30 SEP 2016



**LAND PATTERN RECOMMENDATION**

SCALE 2:1

**NOTES: UNLESS OTHERWISE SPECIFIED**

- A) DOES NOT FULLY CONFORM TO JEDEC REGISTRATION MO-220, ISSUE K.01, DATED AUG 2011.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

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